

# SOT1517-1

LFBGA364, plastic, low profile fine-pitch ball grid array; 364 bumps; 0.8 mm pitch; 17 mm x 17 mm x 1.33 mm body

25 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA364
<b>Package type industry code</b>	LFBGA364
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-275 -MMAC-1
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	08-01-2016
<b>Manufacturer package code</b>	98ASA00418D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.33	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	364	-	



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2 Package outline

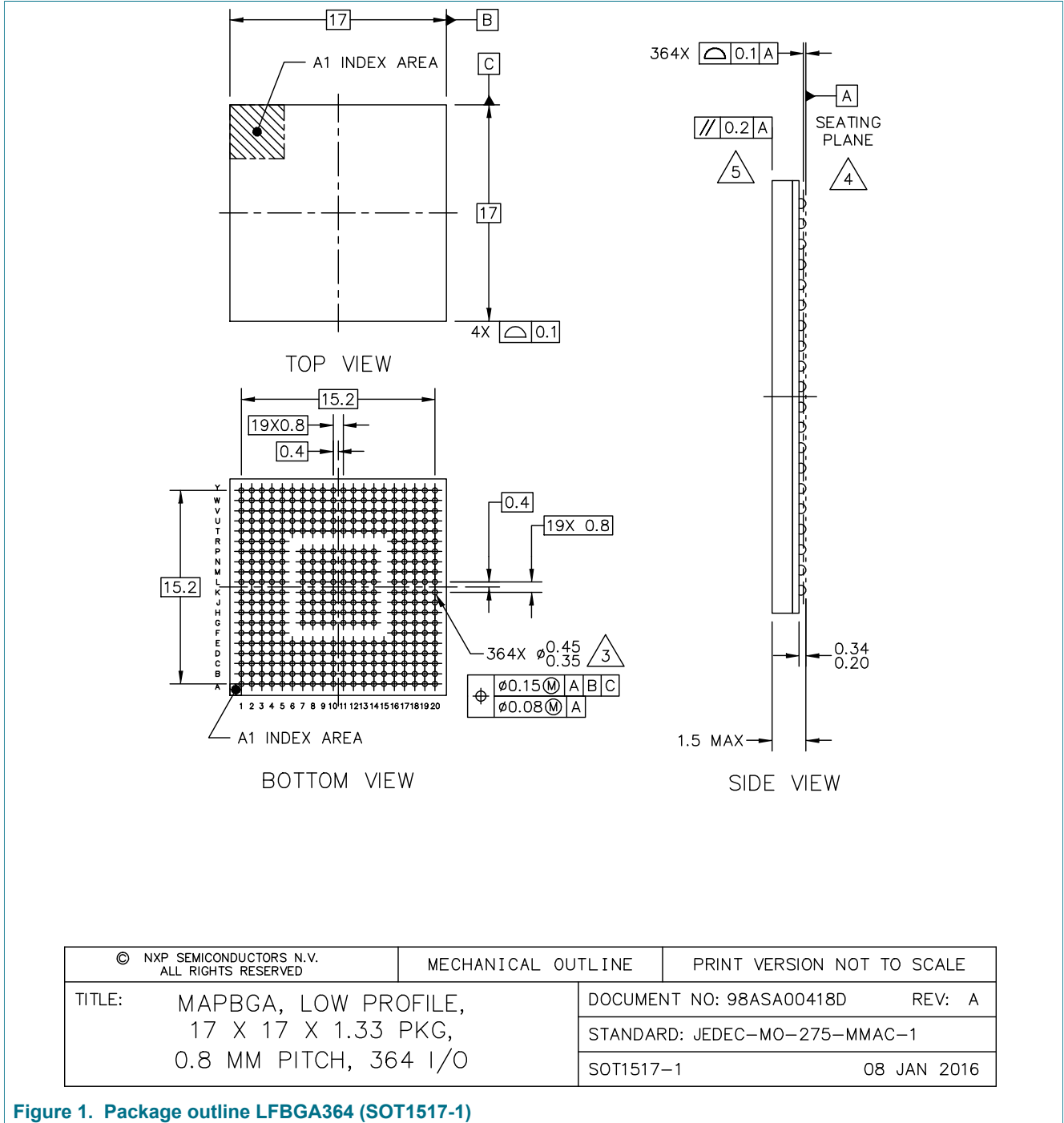


Figure 1. Package outline LFBGA364 (SOT1517-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, LOW PROFILE, 17 X 17 X 1.33 PKG, 0.8 MM PITCH, 364 I/O	DOCUMENT NO: 98ASA00418D	REV: A
	STANDARD: JEDEC-MO-275-MMAC-1	
	SOT1517-1	08 JAN 2016

Figure 2. Package outline note LFBGA364 (SOT1517-1)

### 3 Legal information

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